





TSEV01S01C10

SPECIFICATIONS

- Contact less Temperature Measurement
- Small Size
- Heat Spreader improves Accuracy
- Wide Supply Voltage Range
- Digital Interface Bus (SPI)
- Connector
- Small Field of View

The TSEV01S01C10 is a contact-less temperature measuring system for OEM use based on the detection of infrared radiation.

The TSEV01S01C10 is equipped with an infrared sensor (Thermopile) in front. The Thermopile Sensor has to be pointed at the target object.

The basic working principle is:

- Detection of infrared radiation with a Thermopile sensor, which turns incoming radiation to an analogue voltage
- Determination of sensor temperature using a thermistor
- Calculation of ambient and object temperature using a processing unit
- Providing the ambient and objects temperature at digital output bus (SPI)

The basic thermopile sensor module is suitable for a wide range of application where non-contact temperature measurement and high accuracy are required

FEATURES

0°C – 300°C Measurement Range Small Size Up to 2°C Accuracy 2mA Current Consumption

APPLICATIONS

Contact less Temperature Measurement Climate Control Industrial Process Control Household Applications

ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings are limiting values of permitted operation and should never be exceeded under the worst possible conditions either initially or consequently. If exceeded by even the smallest amount, instantaneous catastrophic failure can occur. And even if the device continues to operate satisfactorily, its life may be considerably shortened.

Parameter	Symbol	ol Conditions		Тур	Max	Unit
Supply Voltage	Vccmax	Stabilized supply voltage	-0.3		16	V
Operating Temperature	Topmax		-10		85	°C
Storage temperature	Tstor		-40		85	°C
Humidity	HumL	-40°C - +50°C			85	%
Humidity	HumH	+50°C - +85°C			50	%

OPERATING CONDITIONS

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Supply Voltage	Vcc	Stabilized supply voltage	3.3		16	V
Operating Temperature Range	Тор		0		85	°C
Emission Coefficient	3		0.98			

SENSOR CONDITIONS

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Field of View	FOV ₁₀	Total field of view at 10% signal level		14		0
Field of View	FOV ₅₀	Total field of view at 50% signal level		10		o
Wavelength Range	S		Silicon, no coating		μm	

OPERATIONAL CHARACTERISTICS

If not otherwise noted, 5V supply voltage and object with ϵ =0.98 were applied.

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Object Temperature Range	Tobj		0		300	°C
Resolution	Res				0.1	°C
Supply Current ¹⁾	1	No output load		2		mΑ
Data Output Rate	Fout			1		Hz
Standard Start-Up Time	tStart				3	S

TOLERANCES

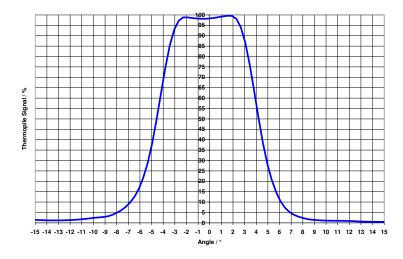
If not otherwise noted, 3.3V supply voltage and object with ϵ =0.98 were applied.

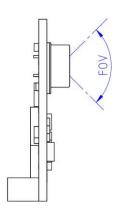
Parameter	Symbol	Sensor Temp.	Object Temp.	Max	Unit
Standard Temp 1) 3)	AccS	15 < T _{sen} < 35	$170 < T_{obj} < 190$	2	°C
Extended Temp. 1 ^{2) 3)}	AccE1	$T_{sen} < 15, T_{sen} > 35$	$170 < T_{obj} < 190$	3	°C
Extended Temp. 2 2) 3)	AccE2	15 < T _{sen} < 35	$T_{obj} < 170, T_{obj} > 190$	3	°C
Extended Temp. 3 ^{2) 3)}	AccE3	$T_{\text{sen}} < 15$, $T_{\text{sen}} > 35$	$T_{obj} < 170, T_{obj} > 190$	4	°C

OTHER TEMPERATURE RANGES AND ACCURACIES ARE AVAILABLE ON REQUEST.

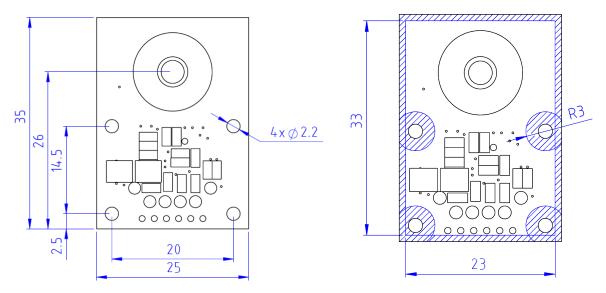
- 1) Proved while production
- ²⁾ Proved by design
- ³⁾ Valid for a distance of 100mm and black body size of 150mm x 150mm

SENSOR FIELD OF VIEW

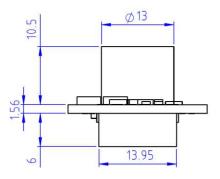




MECHANICAL DIMENSIONS



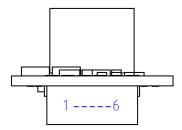
Only use hatched areas for mechanical assembly (screws, nuts, etc).



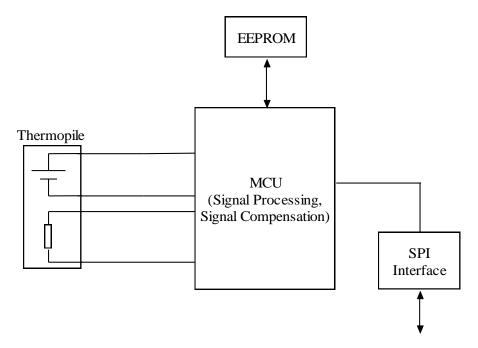
TERMINALS

Connector: JST PHR-6

Pin	Name	Description	Туре
1	VDD	Supply Voltage	Supply
2	GND	Ground	Supply
3	SCL	SPI Clock	Interface
4	MISO	SPI Master In /	Interface
5	MOSI	SPI Master Out /	Interface
6	SCE	SPI Chip Enable	Interface



BLOCK DIAGRAM

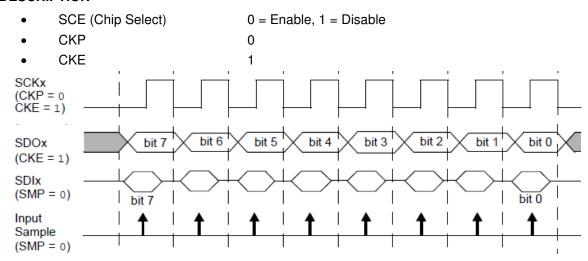


INTERFACE

PARAMETER

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Baudrate	FSPI		10		100	kHz
Data Bits				8		
Chip Select				Yes		
Input Voltage Low					0.9	V
Input Voltage High		Vcc = 3.3V	2.1			V
Output Voltage Low		1mA			0.3	V
Output Voltage High		Vcc = 3.3V, 1mA	3.0			V

SIGNAL DESCRIPTION



SAMPLE CODE

Sample Code for sending 8 bits and reading 8 bits while sending 8 clocks.

```
// Setting directions
       TRISC4 = 1;
                        // SDI = Input
       TRISC5 = 0;
                        // SDO = Output
                        // SCL = Output
       TRISC3 = 0;
// Reset SPI Lines
       RC5 = 0;//SDO
       RC3 = 0;//SCL
       for (c = 0; c < 8; c++)
                cReceive = cReceive << 1;
                                                   // Shift Receive Register
                RC3 = 0:
                                                   //SCL = 0
                RC5 = (cTransmit >> (7 - c));
                                                   // Outupt next Bit on SDO
                RC3 = 1;
                                                   // SCL = 1
                                                           // Input next Bit on SDI
                cReceive = cReceive | RC4;
       RC3 = 0;
       RC5 = 0;
       return cReceive;
```

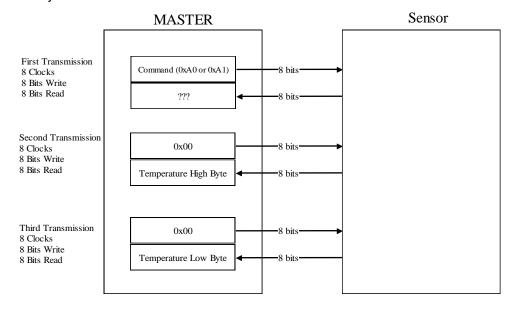
AMBIENT AND OBJECT TEMPERATUREMEASUREMENT

Please refer following table for SPI commands to read object temperature and ambient temperature. Both values are transmitted in hundredth of degrees.

Com	Description	Reply	Bytes
0xA0	Sensor Temperature	Sensor temperature in hundredth of degrees Celsius	2
0xA1	Object Temperature	Object temperature in hundredth of degrees Celsius	2

SEQUENCE OF TRANSMISSION

Enable SCE (SCE=0) before transmission of "Command". Release SCE (SCE=1) after reading last byte.



EXAMPLE OF TEMPERATURE CALCULATION

For reading object temperature send: 0xA1

Return values i.e.:

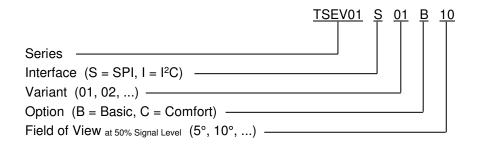
Byte(0) = ??? discard reading

Byte(1) = 0x1A (=26)

Byte(2) = 0xB0 (=176)

Tobj = (256 * Byte(1) + Byte(2)) / 100 = (256 * 26 + 176) / 100 = 68.32°C

NAMING CONVENTION



ORDER INFORMATION

Please order this product using following:

Part Number Part Description
G-TPMO-023 TSEV01S01C10

EMC

Due to the use of these modules for OEM application no CE declaration is done.

Especially line coupled disturbances like surge, burst, HF etc. cannot be removed by the module due to the small board area and low price feature. There is no protection circuit against reverse polarity or over voltage implemented.

The module will be designed using capacitors for blocking and ground plane areas in order to prevent wireless coupled disturbances as good as possible.

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